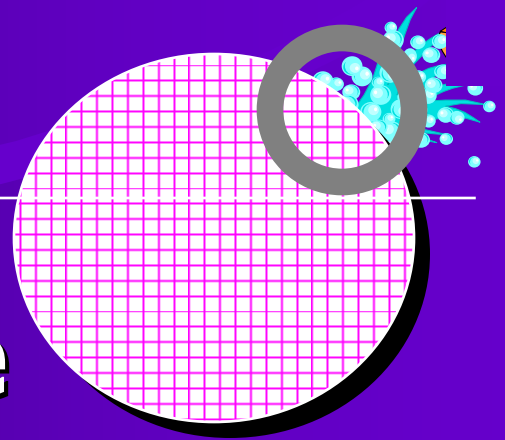


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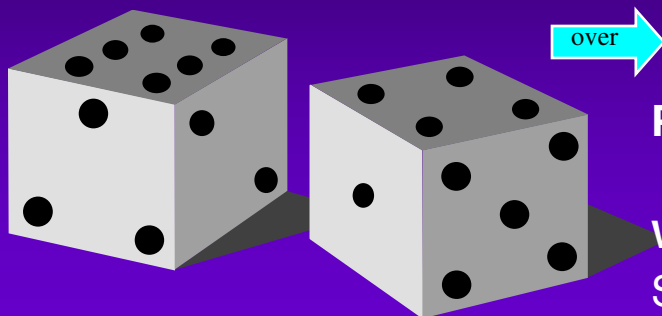
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With facilities on both East and West Coasts, Valley Design offers increased capacity in advanced high-speed CNC dicing, cutting and sawing, enabling us to provide a complete spectrum of shapes and materials.



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SALES & CUSTOMER SERVICE

Phone: 831.420.0595

FAX: 831.420.0592

e-mail: sales@valleydesign.com

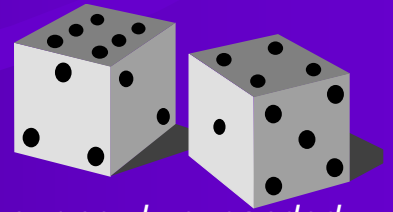
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Santa Cruz, CA

EAST

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Don't Leave Your Dicing Jobs to Chance!



Valley Design now offers expanded capacity and service with our newly expanded 30,000 sq.ft. facilities in Santa Cruz, CA and Shirley, MA. With over 30 years of precision dicing and machining experience, Valley Design is fully equipped to handle even your most challenging projects.

Our fully programmable dicing saws are equipped with 200X microscopes and video screens to ensure precision alignment.

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CAPABILITIES

- Chip sizes as small as .005" sq.
- Kerf as low as 20 microns
- Material sizes up to 8" x 18" any thickness
- *Ultra-thin* materials diced to 10 microns thick with edge chipping less than 2 microns
- Mounting methods include UV cured or sticky tape, hard carrier, or wax mount
- Blade inventory includes diamond and super abrasives in all sizes and grits using resin bond, metal bond or plated technology

What Else Does Valley Design Do?

Valley Design, an ISO 9001:2000 certified company, has been a leader in materials processing for over 25 years. Valley offers precision lapping, polishing, dicing, edge/angle polishing, thinning, fiber array polishing, bonding, coating, grinding, shaping and wafering services. The company specializes in *ultra-thin* (as thin as 12.5 microns), *ultra-flat* (1/20 Wave) *super-polishing* (< 10/5 scratch/dig or 5-10 Angstroms) and tight tolerances (+/- 1 micron).

Applications and products include substrates, windows, wafers, stock and custom flat optical components, subassemblies, beamsplitters, polarizers, DWDM filter substrates, glass rods/blocks/spacers, lenses, mirrors, prisms, SEMI standard dummy wafers, solar cells, waveguides, wedges, laser diodes.

Valley enjoys extensive experience with a wide variety of materials, and is also willing to work with proprietary materials. Valley routinely processes Fused Silica, Quartz, Optical Glass, AlN, Pyrex, 99.6% and 96% Alumina, Sapphire, AF45, BK7, B270, D263, LASFN9, 1737, 7070, Ceramics, GaAs, InP, ZnS, ZnSe, PZT, PLZT, Lithium Niobate, Borosilicates, Soda Lime, Crystals, Silicon and Metals. The company also has extensive stock in Fused Silica, Silicon, Soda Lime, Aluminum Nitride, Sapphire and 96%/99.6% Alumina.

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